

44.) (Twice Amended) A method of attaching a semiconductor die to an organic support structure, comprising:

affixing a first side of a two-sided adhesive tape to a surface of the organic support structure, wherein adhesive of the adhesive tape comprises a pressure sensitive, thermosetting adhesive;

elevating the temperature of the tape to activate the first side of the adhesive tape;

applying pressure to the tape and organic support structure to laminate the adhesive tape to the organic support structure, wherein elevating the temperature and applying pressure occurs for 100ms;

affixing a face of the semiconductor die to a second side of the adhesive tape;

elevating the temperature of the tape to activate the second side of the adhesive tape;

applying pressure to the die and organic support structure to laminate the adhesive tape to the die;

wire bonding bond wires to a plurality of bond pads on the die face with a plurality of lead connections on the organic support structure;

applying an encapsulating material over the bond pads, bond wires, lead connections, and a portion of the die face and support structure.

63.) (Amended) The method of claim 34 wherein the adhesive tape includes a carrier layer, the adhesive tape has a lamination temperature of less than or equal to approximately 100 degrees C, each adhesive layer ha[ving]s a thickness of .0005 inches, and the carrier layer having a thickness of .002 inches.

REMARKS

Applicant has reviewed the Office Action mailed on July 17, 2001, and the references cited therewith. Claims 39, 44, and 63 are amended; claims 34 - 63 are now pending in this application.